FAIRCHILD
SEMICONDUCTOR TM

November 1995

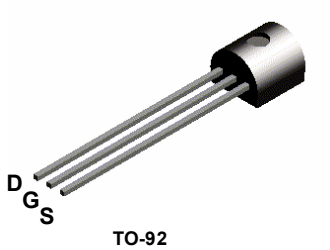
2N7000 / 2N7002 / NDS7002A
N-Channel Enhancement Mode Field Effect Transistor

General Description

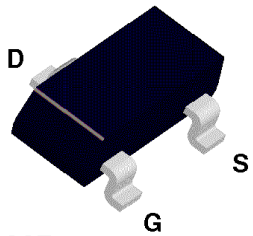
These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 400mA DC and can deliver pulsed currents up to 2A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

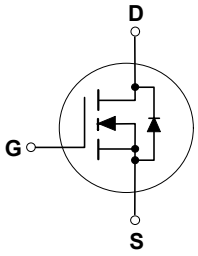
- High density cell design for low $R_{DS(ON)}$.
- Voltage controlled small signal switch.
- Rugged and reliable.
- High saturation current capability.



TO-92



SOT-23



Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	2N7000	2N7002	NDS7002A	Units
V_{DSS}	Drain-Source Voltage	60			V
V_{DGR}	Drain-Gate Voltage ($R_{GS} \leq 1$ MΩ)	60			V
V_{GSS}	Gate-Source Voltage - Continuous	±20			V
	- Non Repetitive (tp < 50µs)	±40			
I_D	Maximum Drain Current - Continuous	200	115	280	mA
	- Pulsed	500	800	1500	
P_D	Maximum Power Dissipation	400	200	300	mW
	Derated above 25°C	3.2	1.6	2.4	mW/°C
T_J,T_{STG}	Operating and Storage Temperature Range	-55 to 150		-65 to 150	°C
T_L	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	300			°C
THERMAL CHARACTERISTICS					
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	312.5	625	417	°C/W

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Type	Min	Typ	Max	Units
OFF CHARACTERISTICS							
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS} = 0 V, I_D = 10 µA	All	60			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 48 V, V_{GS} = 0 V	2N7000			1	µA
		T_J=125°C				1	mA
		V_{DS} = 60 V, V_{GS} = 0 V	2N7002 NDS7002A			1	µA
		T_J=125°C				0.5	mA
I_{GSSF}	Gate - Body Leakage, Forward	V_{GS} = 15 V, V_{DS} = 0 V	2N7000			10	nA
		V_{GS} = 20 V, V_{DS} = 0 V	2N7002 NDS7002A			100	nA
I_{GSSR}	Gate - Body Leakage, Reverse	V_{GS} = -15 V, V_{DS} = 0 V	2N7000			-10	nA
		V_{GS} = -20 V, V_{DS} = 0 V	2N7002 NDS7002A			-100	nA
ON CHARACTERISTICS (Note 1)							
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 1 mA	2N7000	0.8	2.1	3	V
		V_{DS} = V_{GS}, I_D = 250 µA	2N7002 NDS7002A	1	2.1	2.5	
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS} = 10 V, I_D = 500 mA	2N7000		1.2	5	Ω
		T_J =125°C			1.9	9	
		V_{GS} = 4.5 V, I_D = 75 mA			1.8	5.3	
		V_{GS} = 10 V, I_D = 500 mA	2N7002		1.2	7.5	
		T_J =100°C			1.7	13.5	
		V_{GS} = 5.0 V, I_D = 50 mA			1.7	7.5	
		T_J =100C			2.4	13.5	
		V_{GS} = 10 V, I_D = 500 mA	NDS7002A		1.2	2	
		T_J =125°C			2	3.5	
		V_{GS} = 5.0 V, I_D = 50 mA			1.7	3	
		T_J =125°C			2.8	5	
$V_{DS(ON)}$	Drain-Source On-Voltage	V_{GS} = 10 V, I_D = 500 mA	2N7000		0.6	2.5	V
		V_{GS} = 4.5 V, I_D = 75 mA			0.14	0.4	
		V_{GS} = 10 V, I_D = 500mA	2N7002		0.6	3.75	
		V_{GS} = 5.0 V, I_D = 50 mA			0.09	1.5	
		V_{GS} = 10 V, I_D = 500mA	NDS7002A		0.6	1	
		V_{GS} = 5.0 V, I_D = 50 mA			0.09	0.15	

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Type	Min	Typ	Max	Units
ON CHARACTERISTICS Continued (Note 1)							
$I_{D(ON)}$	On-State Drain Current	V_{GS} = 4.5 V, V_{DS} = 10 V	2N7000	75	600		mA
		V_{GS} = 10 V, $V_{DS} \geq 2\ V_{DS(on)}$	2N7002	500	2700		
		V_{GS} = 10 V, $V_{DS} \geq 2\ V_{DS(on)}$	NDS7002A	500	2700		
g_{FS}	Forward Transconductance	V_{DS} = 10 V, I_D = 200 mA	2N7000	100	320		mS
		$V_{DS} \geq 2\ V_{DS(on)}$, I_D = 200 mA	2N7002	80	320		
		$V_{DS} \geq 2\ V_{DS(on)}$, I_D = 200 mA	NDS7002A	80	320		
DYNAMIC CHARACTERISTICS							
C_{iss}	Input Capacitance	V_{DS} = 25 V, V_{GS} = 0 V, f = 1.0 MHz	All		20	50	pF
C_{oss}	Output Capacitance		All		11	25	pF
C_{rss}	Reverse Transfer Capacitance		All		4	5	pF
t_{on}	Turn-On Time	V_{DD} = 15 V, R_L = 25 Ω, I_D = 500 mA, V_{GS} = 10 V, R_{GEN} = 25	2N7000			10	ns
		V_{DD} = 30 V, R_L = 150 Ω, I_D = 200 mA, V_{GS} = 10 V, R_{GEN} = 25 Ω	2N700 NDS7002A			20	
t_{off}	Turn-Off Time	V_{DD} = 15 V, R_L = 25 Ω, I_D = 500 mA, V_{GS} = 10 V, R_{GEN} = 25	2N7000			10	ns
		V_{DD} = 30 V, R_L = 150 Ω, I_D = 200 mA, V_{GS} = 10 V, R_{GEN} = 25 Ω	2N700 NDS7002A			20	
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS							
I_S	Maximum Continuous Drain-Source Diode Forward Current		2N7002			115	mA
			NDS7002A			280	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		2N7002			0.8	A
			NDS7002A			1.5	
V_{SD}	Drain-Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 115 mA (Note 1)	2N7002		0.88	1.5	V
		V_{GS} = 0 V, I_S = 400 mA (Note 1)	NDS7002A		0.88	1.2	

Note:
1. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%.

Typical Electrical Characteristics

2N7000 / 2N7002 / NDS7002A

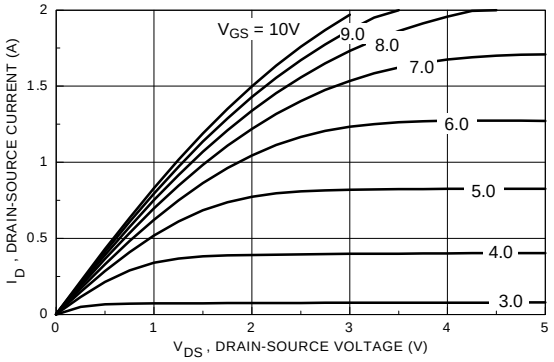


Figure 1. On-Region Characteristics

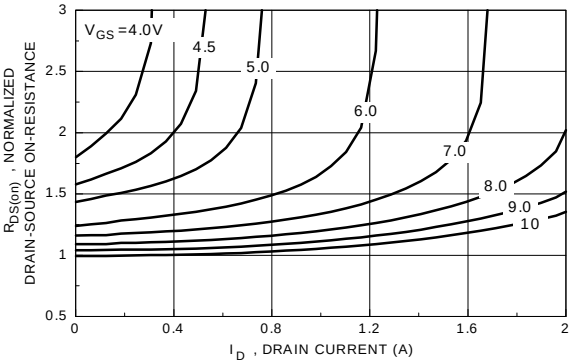


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current

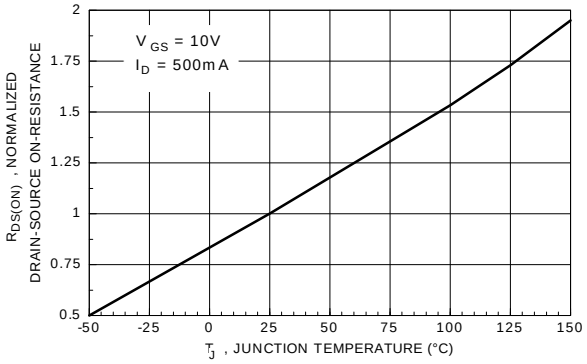


Figure 3. On-Resistance Variation with Temperature

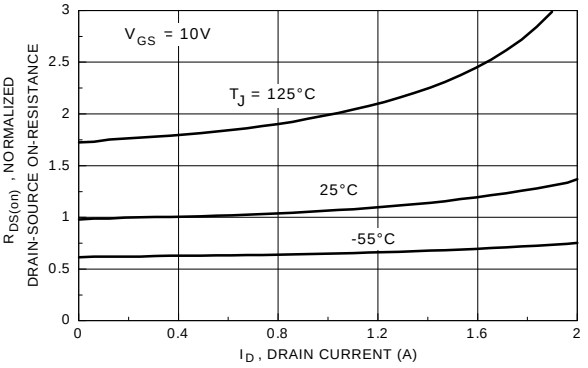


Figure 4. On-Resistance Variation with Drain Current and Temperature

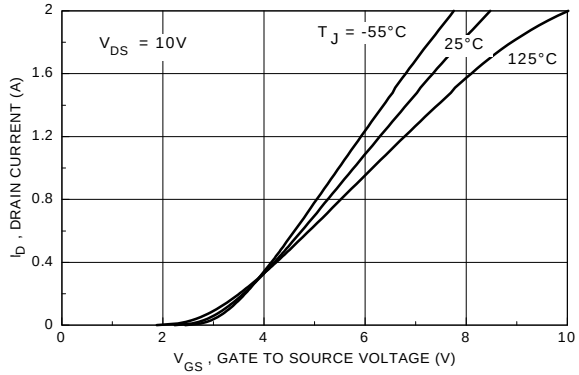


Figure 5. Transfer Characteristics

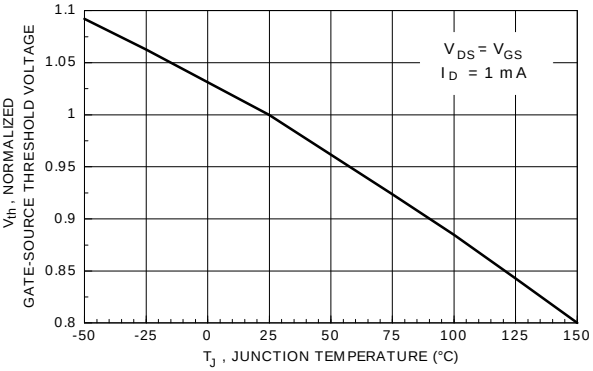


Figure 6. Gate Threshold Variation with Temperature

Typical Electrical Characteristics (continued)

2N7000 / 2N7002 /NDS7002A

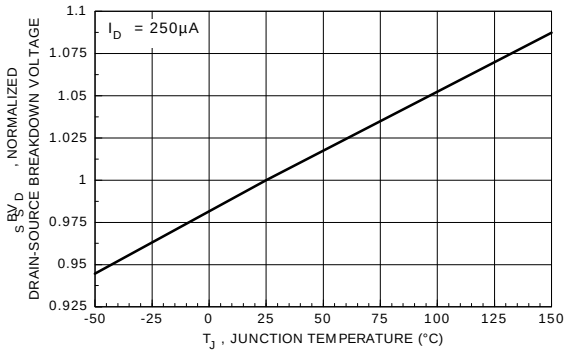


Figure 7. Breakdown Voltage Variation with Temperature

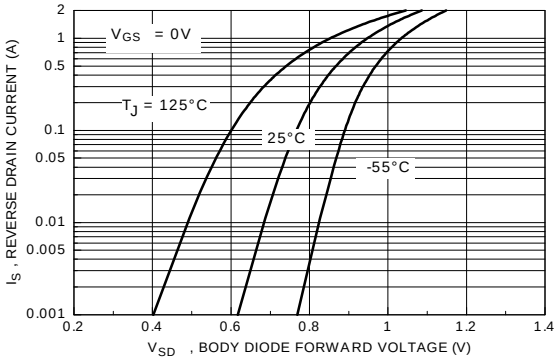


Figure 8. Body Diode Forward Voltage Variation with Current and Temperature

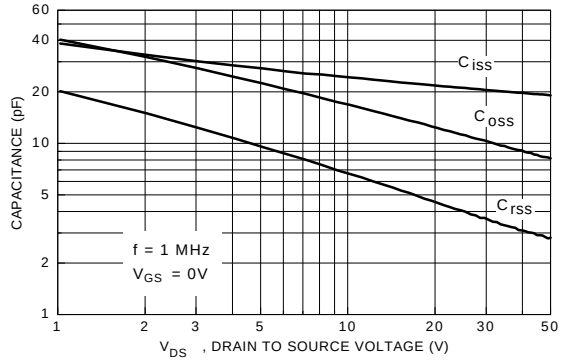


Figure 9. Capacitance Characteristics

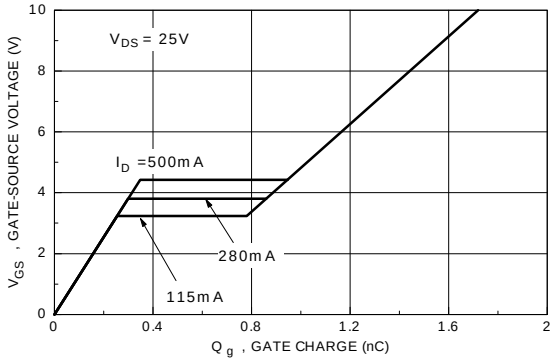


Figure 10. Gate Charge Characteristics

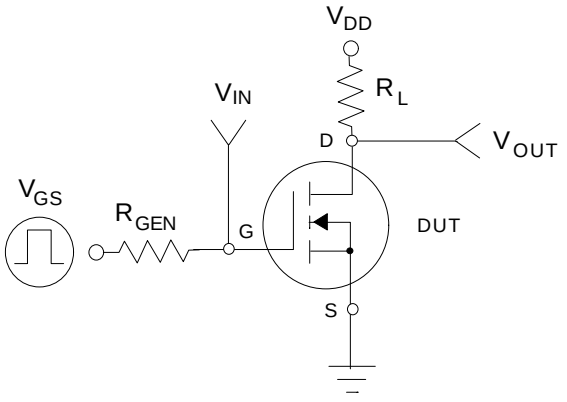


Figure 11. Switching Test Circuit

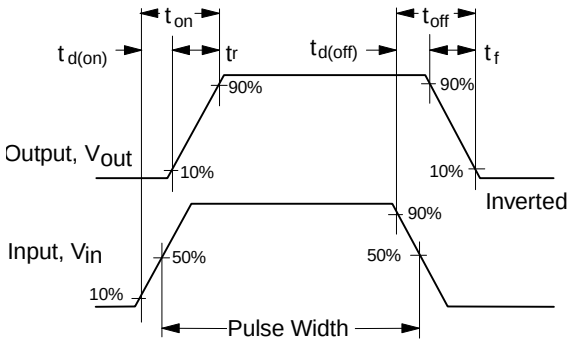


Figure 12. Switching Waveforms

Typical Electrical Characteristics (continued)

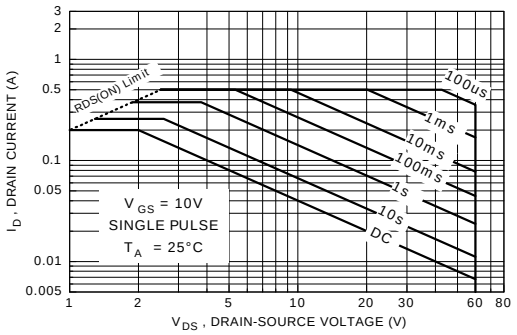


Figure 13. 2N7000 Maximum Safe Operating Area

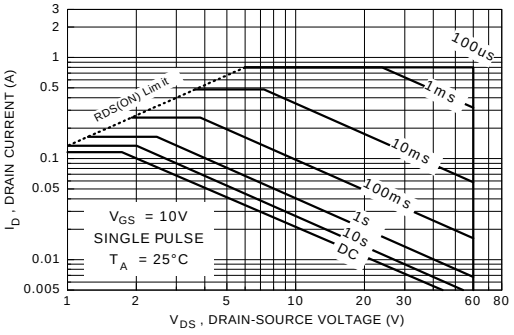


Figure 14. 2N7002 Maximum Safe Operating Area

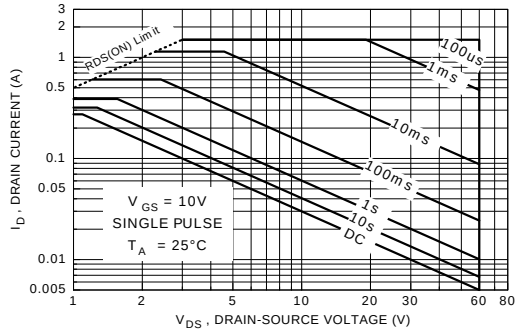


Figure 15. NDS7000A Maximum Safe Operating Area

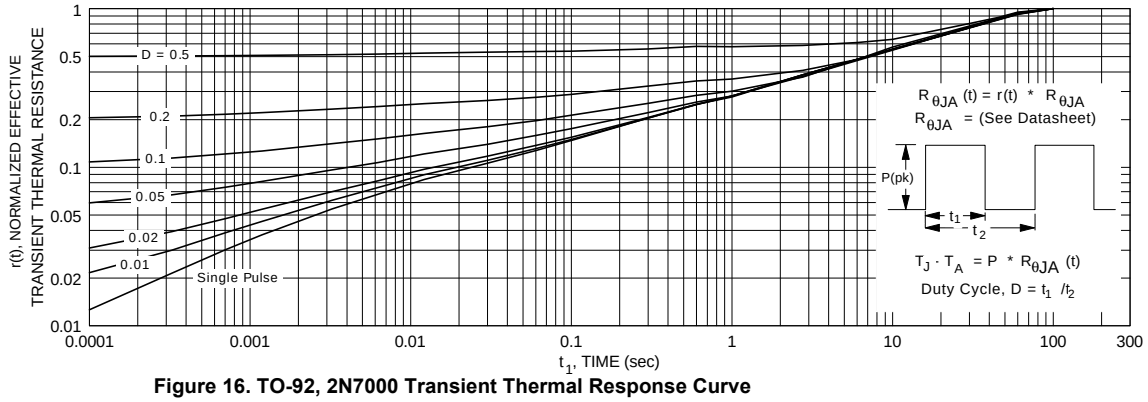


Figure 16. TO-92, 2N7000 Transient Thermal Response Curve

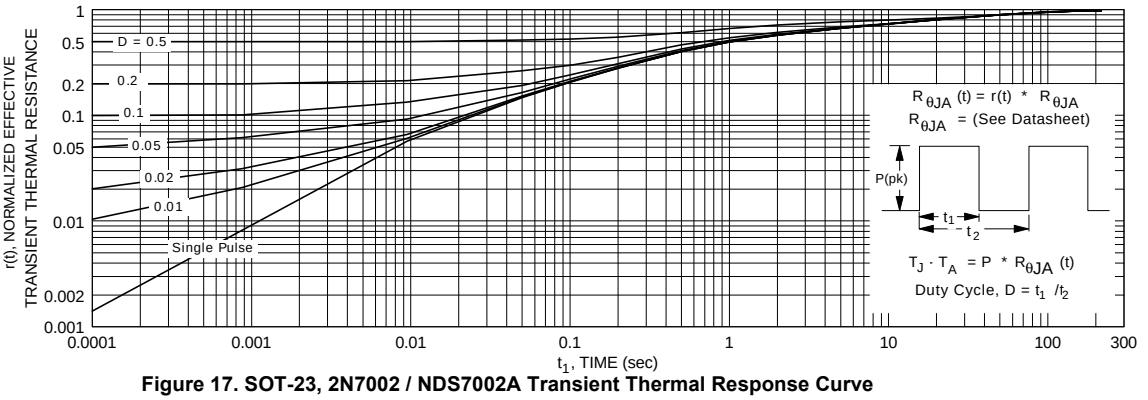


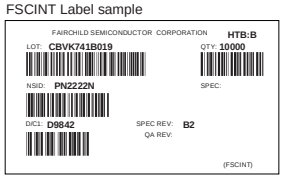
Figure 17. SOT-23, 2N7002 / NDS7002A Transient Thermal Response Curve

TO-92 Tape and Reel Data and Package Dimensions

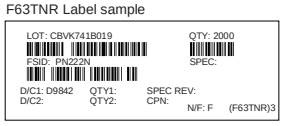
FAIRCHILD SEMICONDUCTOR™

TO-92 Packaging
Configuration: Figure 1.0

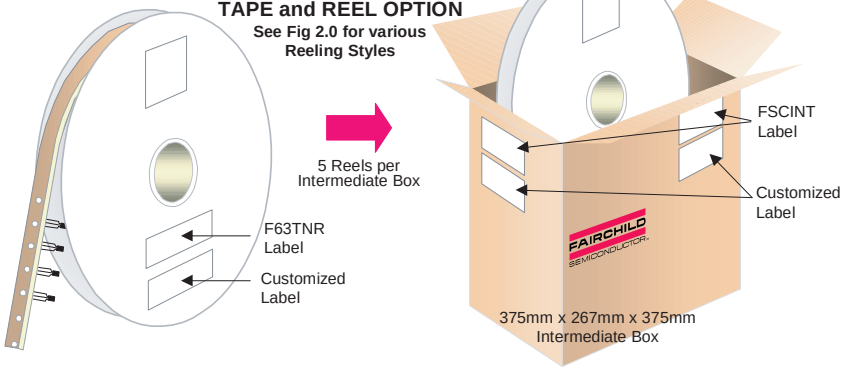
FSCINT Label sample



F63TNR Label sample



TAPE and REEL OPTION
See Fig 2.0 for various Reeling Styles

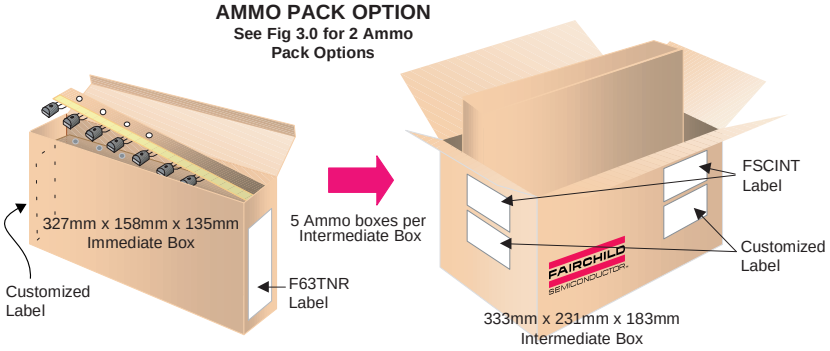


TO-92 TNR/AMMO PACKING INFROMATION

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	E	2,000	D27Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm
Reel weight with components = 1.04 kg
Ammo weight with components = 1.02 kg
Max quantity per intermediate box = 10,000 units

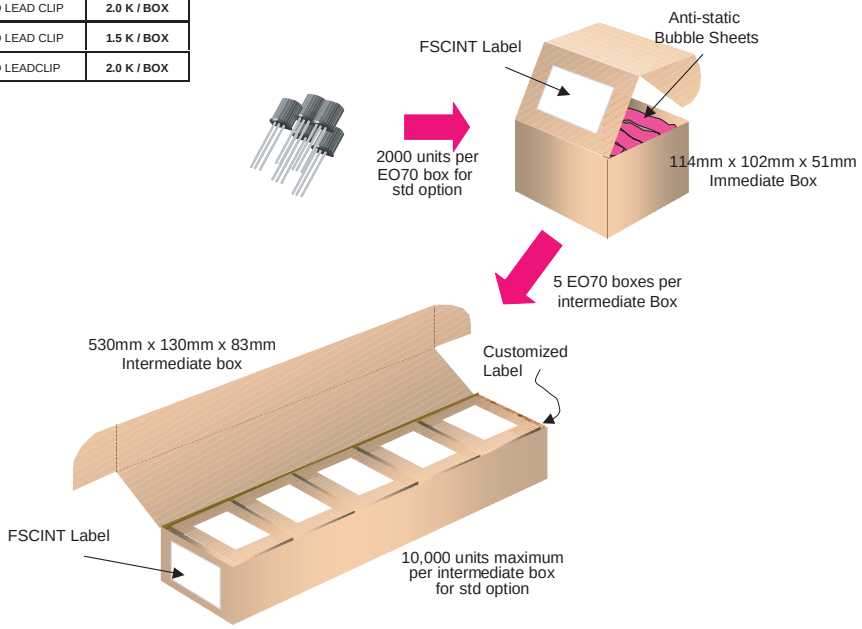
AMMO PACK OPTION
See Fig 3.0 for 2 Ammo Pack Options



(TO-92) BULK PACKING INFORMATION

EOL CODE	DESCRIPTION	LEADCLIP DIMENSION	QUANTITY
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0 K / BOX
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5 K / BOX
NO EOL CODE	TO-92 STANDARD STRAIGHT	NO LEADCLIP	2.0 K / BOX

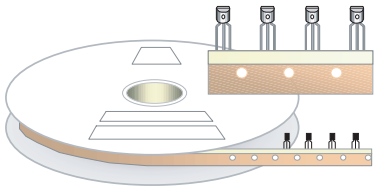
BULK OPTION
See Bulk Packing Information table



TO-92 Tape and Reel Data and Package Dimensions, continued

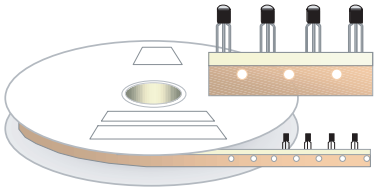
TO-92 Reeling Style
Configuration: Figure 2.0

Machine Option “A” (H)



Style “A”, D26Z, D70Z (s/h)

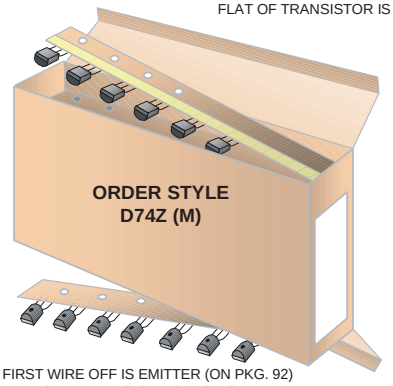
Machine Option “E” (J)



Style “E”, D27Z, D71Z (s/h)

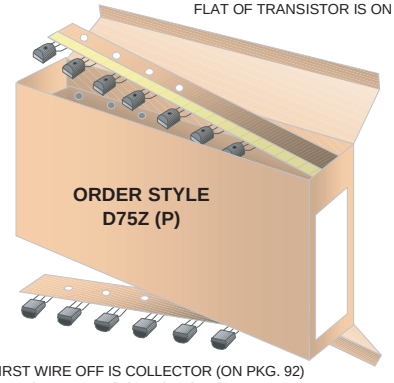
TO-92 Radial Ammo Packaging
Configuration: Figure 3.0

FIRST WIRE OFF IS COLLECTOR
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON TOP



FIRST WIRE OFF IS EMITTER (ON PKG. 92)
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON BOTTOM

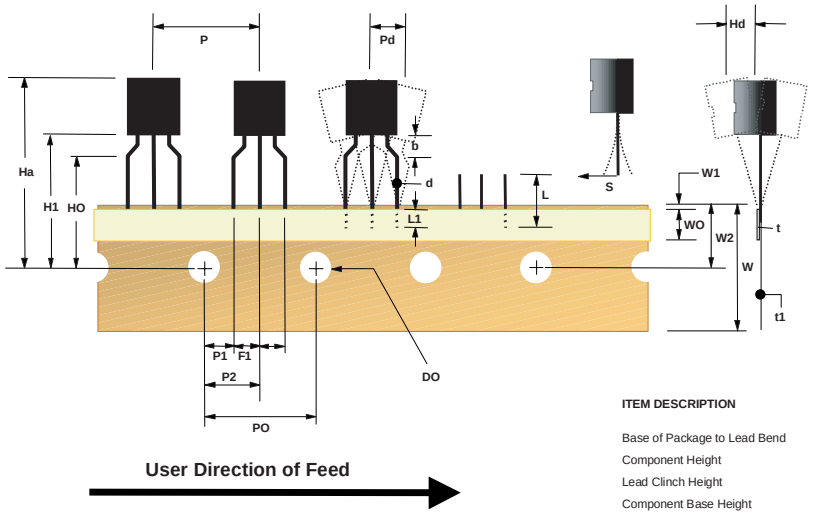
FIRST WIRE OFF IS EMITTER
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON BOTTOM



FIRST WIRE OFF IS COLLECTOR (ON PKG. 92)
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON TOP

TO-92 Tape and Reel Data and Package Dimensions, continued

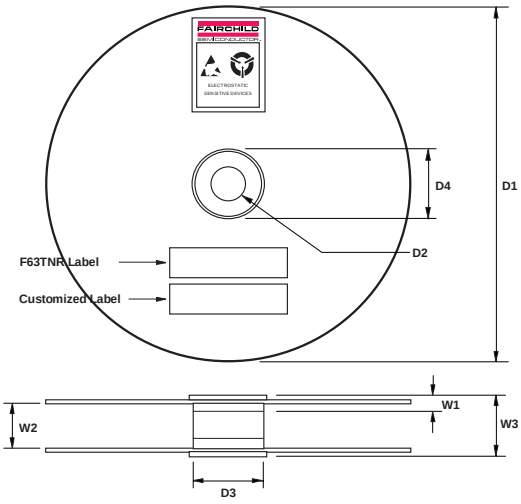
TO-92 Tape and Reel Taping
Dimension Configuration: Figure 4.0



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Ha	0.928 (+/- 0.025)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0 .010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note : All dimensions are in inches.

TO-92 Reel
Configuration: Figure 5.0

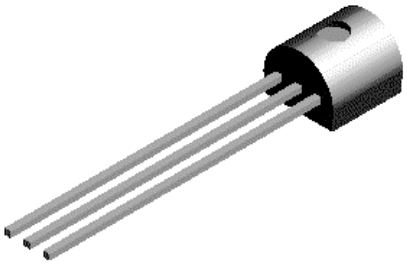


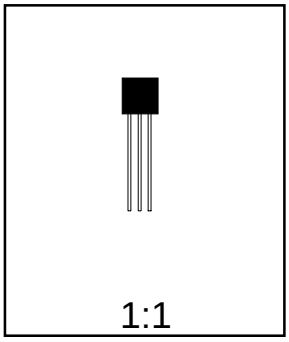
ITEM DESCRIPTION	SYSMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are inches

TO-92 Tape and Reel Data and Package Dimensions

TO-92 (FS PKG Code 92, 94, 96)





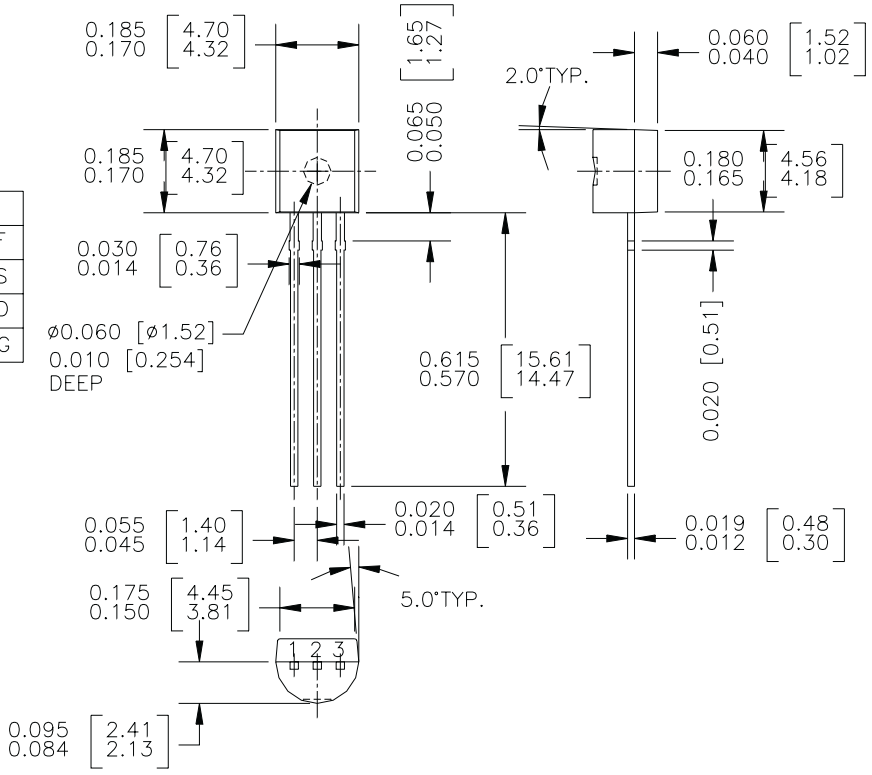
Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.1977

TO−92 (92,94,96)

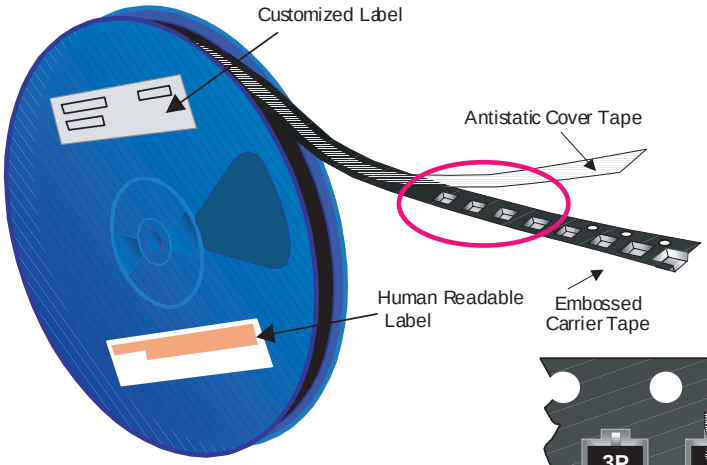
PIN	92		94		96	
	B	F	B	F	B	F
1	E	D	E	D	B	S
2	B	S	C	G	E	D
3	C	G	B	S	C	G



SOT-23 Tape and Reel Data and Package Dimensions

FAIRCHILD SEMICONDUCTOR™

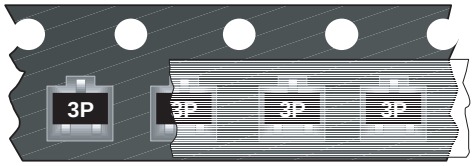
SOT-23 Packaging Configuration: Figure 10



Packaging Description:

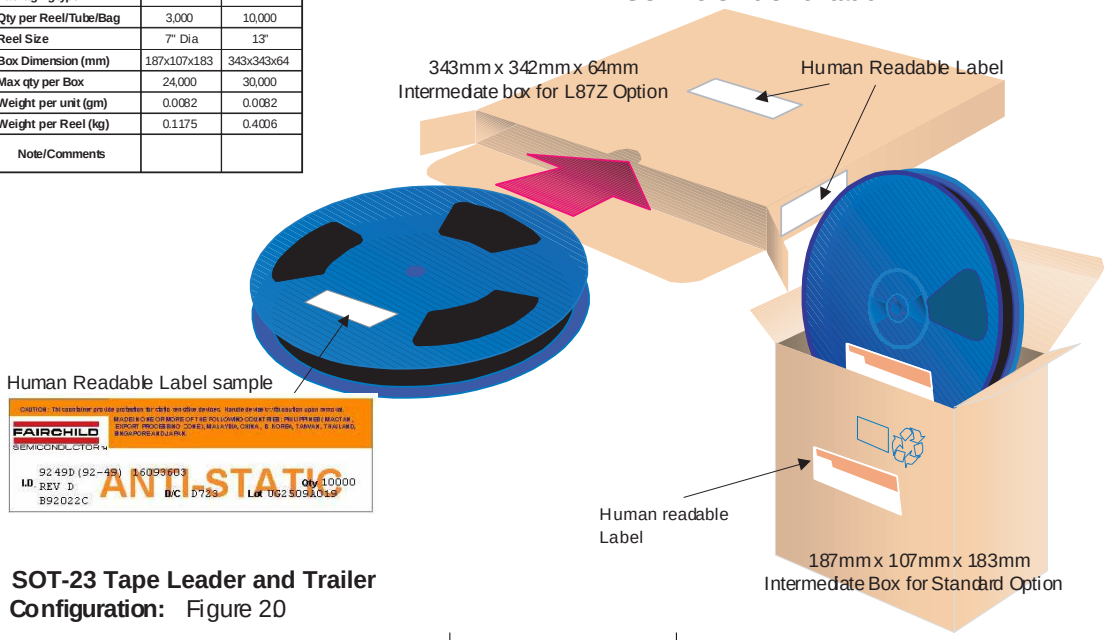
SOT-23 parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177cm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table.

These full reels are individually labeled and placed inside a standard intermediate made of recyclable corrugated brown paper with a Fairchild logo printing. One pizza box contains eight reels maximum. And these intermediate boxes are placed inside a labeled shipping box which comes in different sizes depending on the number of parts shipped.

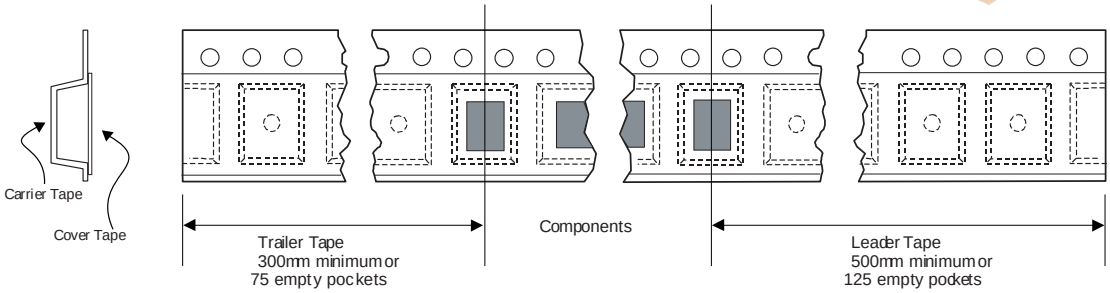


SOT-23 Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	187x107x183	343x343x64
Max qty per Box	24,000	30,000
Weight per unit (gm)	0.0082	0.0082
Weight per Reel (kg)	0.1175	0.4006
Note/Comments		

SOT-23 Unit Orientation

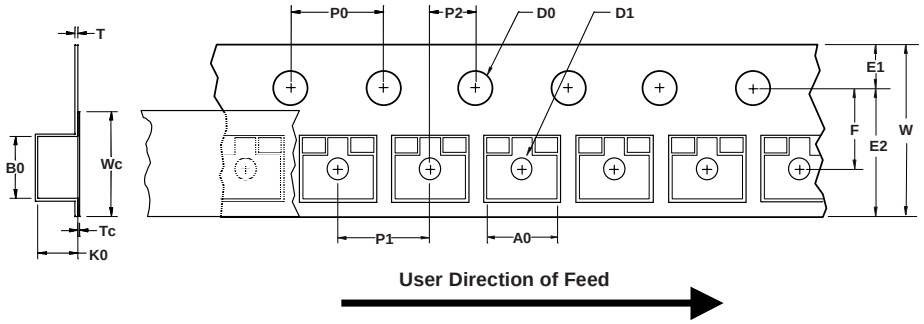


SOT-23 Tape Leader and Trailer Configuration: Figure 20



SOT-23 Tape and Reel Data and Package Dimensions, continued

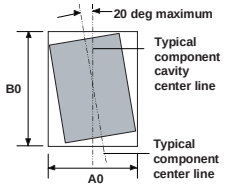
SOT-23 Embossed Carrier Tape
Configuration: Figure 3.0



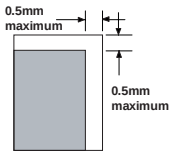
Dimensions are in millimeter														
Pkg type	**A0**	**B0**	**W**	**D0**	**D1**	**E1**	**E2**	**F**	**P1**	**P0**	**K0**	**T**	**Wc**	**Tc**
SOT-23 (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).

Sketch A (Side or Front Sectional View)
Component Rotation

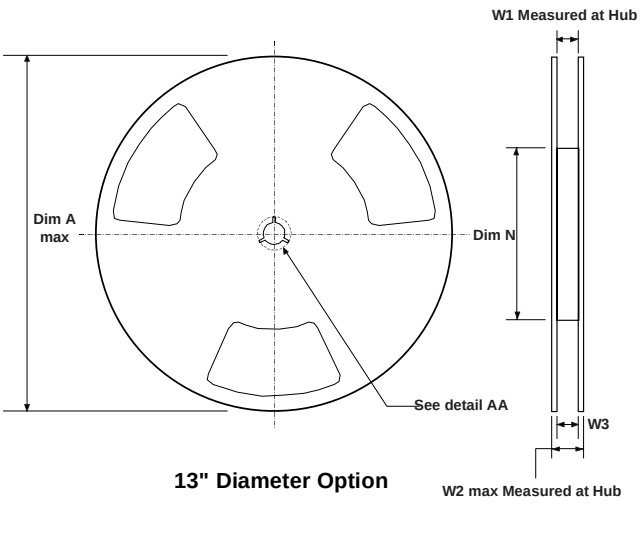


Sketch B (Top View)
Component Rotation

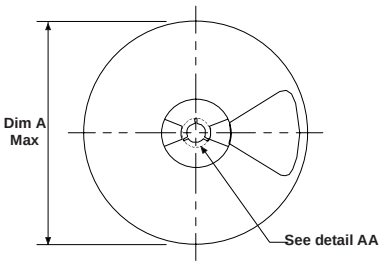


Sketch C (Top View)
Component lateral movement

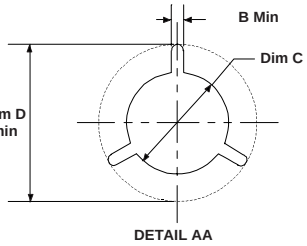
SOT-23 Reel Configuration: Figure 4.0



13" Diameter Option



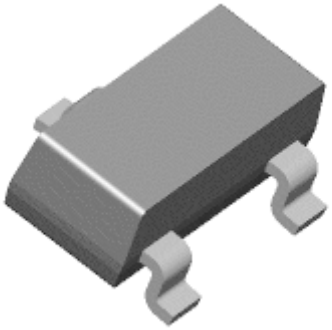
7" Diameter Option

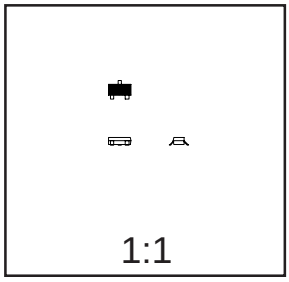


Dimensions are in inches and millimeters									
Tape Size	**Reel Option**	**Dim A**	**Dim B**	**Dim C**	**Dim D**	**Dim N**	**Dim W1**	**Dim W2**	**Dim W3 (LSL-USL)**
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 – 0.429 7.9 – 10.9

SOT-23 Tape and Reel Data and Package Dimensions, continued

SOT-23 (FS PKG Code 49)

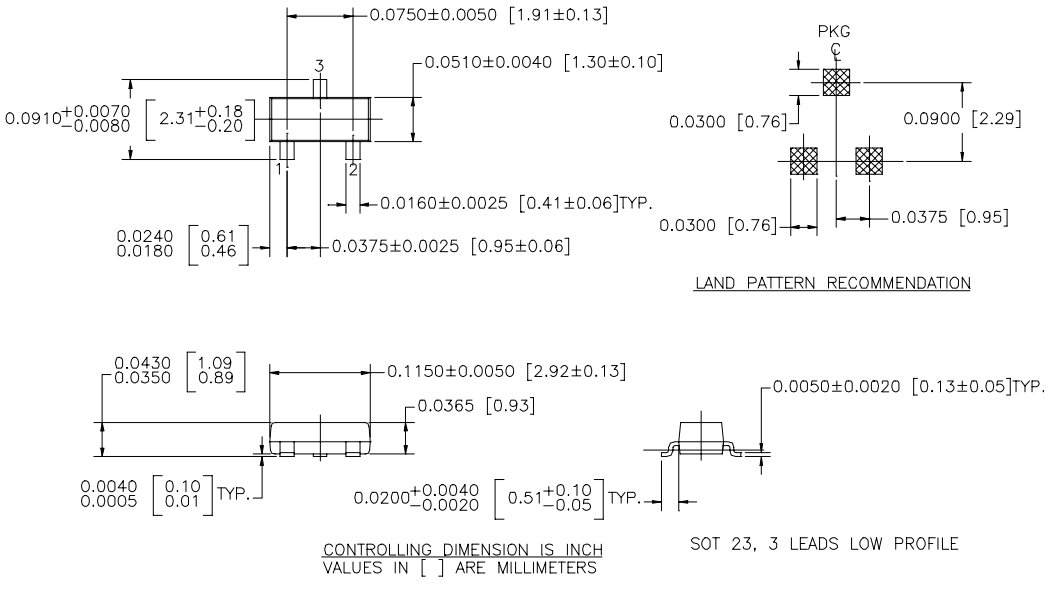




Scale 1:1 on letter size paper

Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.0082



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2. REFERENCE JEDEC REGISTRATION TO−236, VARIATION AB, ISSUE G, DATED JUL 1993

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